

# 電機資訊學院 2026 作 BRAIN PLUS HAND 實作專題競賽

## Monolithic 3D Hetero-Integration Enabled by BEOL MoS<sub>2</sub>-nFDFET and Si-pFinFET

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**Abstract:** In this study, we demonstrate BEOL-compatible fabrication processes for n-type transistor with MoS<sub>2</sub>. Our MoS<sub>2</sub> n-type Fully Depleted FET (nFDFET) demonstrate excellent gate control and high on/off current ratio (10<sup>9</sup>). Furthermore, we realized a hybrid CFET architecture through hetero-integration of MoS<sub>2</sub>-nFDFET and Si-pFinFET and successively implement basic logic elements e.g., inverter, NAND, and NOR. These findings highlight the advantages of 2D material in advancing next-generation logic circuits and 3D integrated systems.

### Characteristics of MoS<sub>2</sub>

2D materials with atomic thickness, high mobility and dangling-bond-free surface exhibit advantages and facilitate M3D hetero-integration. MoS<sub>2</sub> exhibits n-type characteristics and a high direct bandgap of ~1.8 eV. There are mature growth and transfer techniques for MoS<sub>2</sub>.

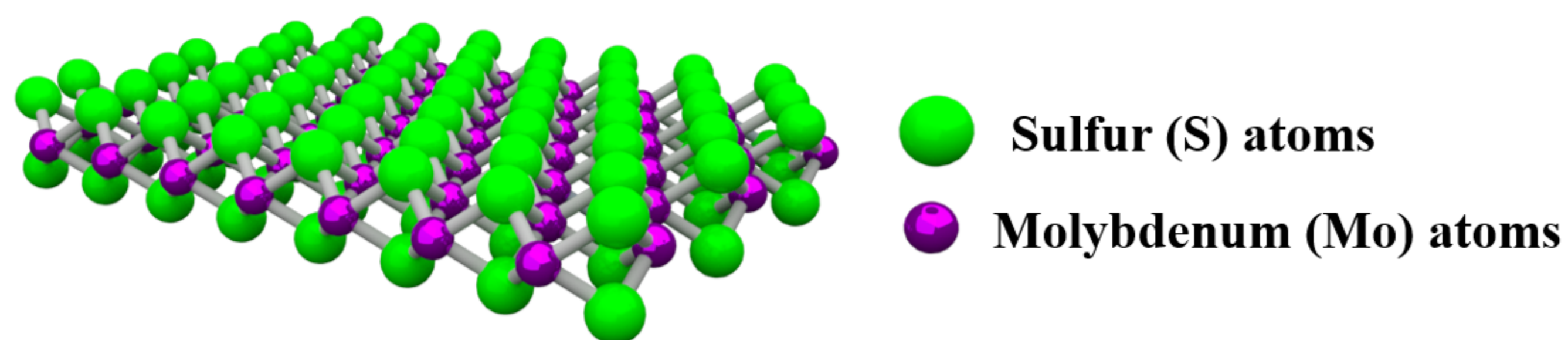


Fig. 1 Structure of MoS<sub>2</sub>.

### Experiment Process

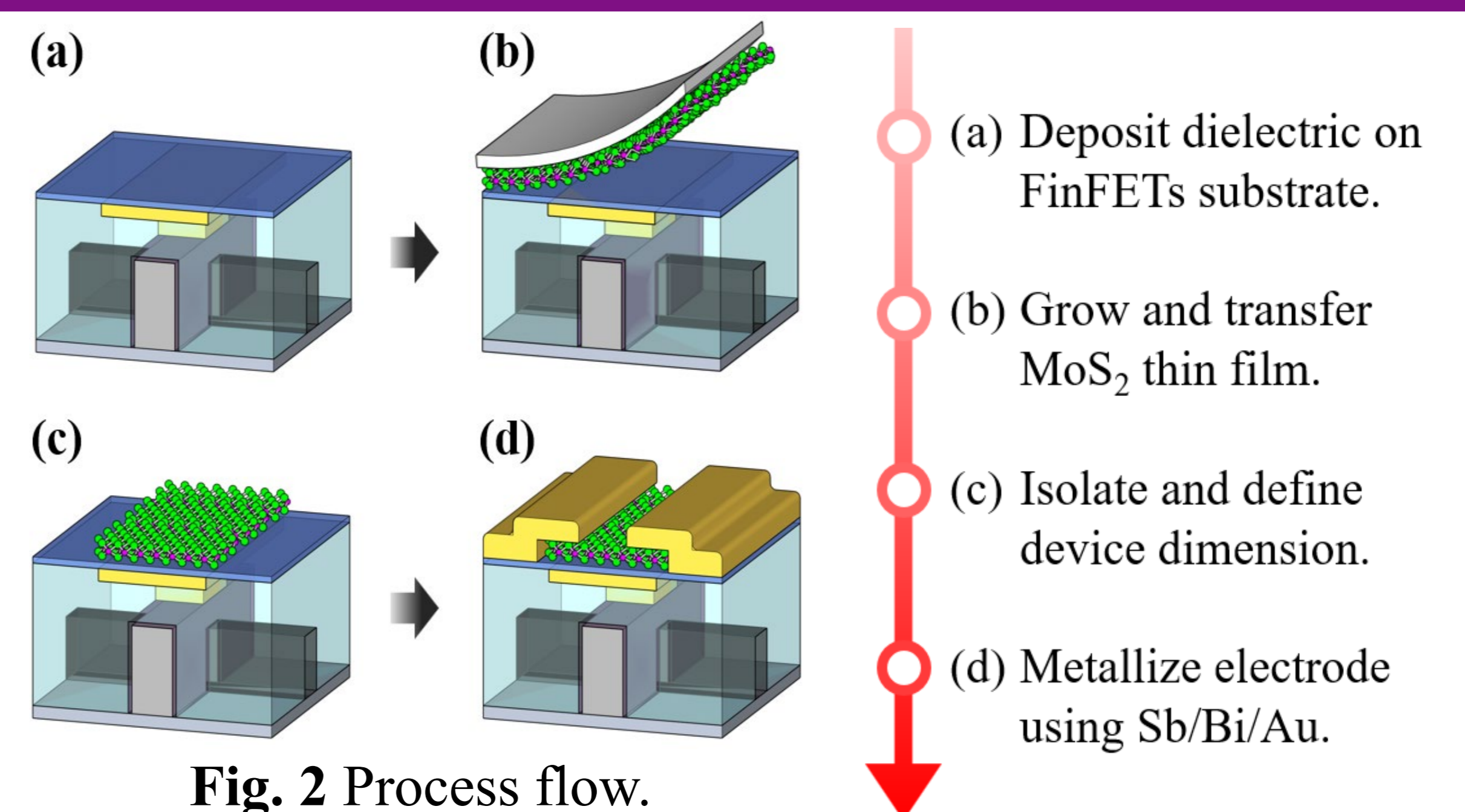


Fig. 2 Process flow.

### Experiment Results

#### 1. MoS<sub>2</sub> n-type Fully Depleted FETs

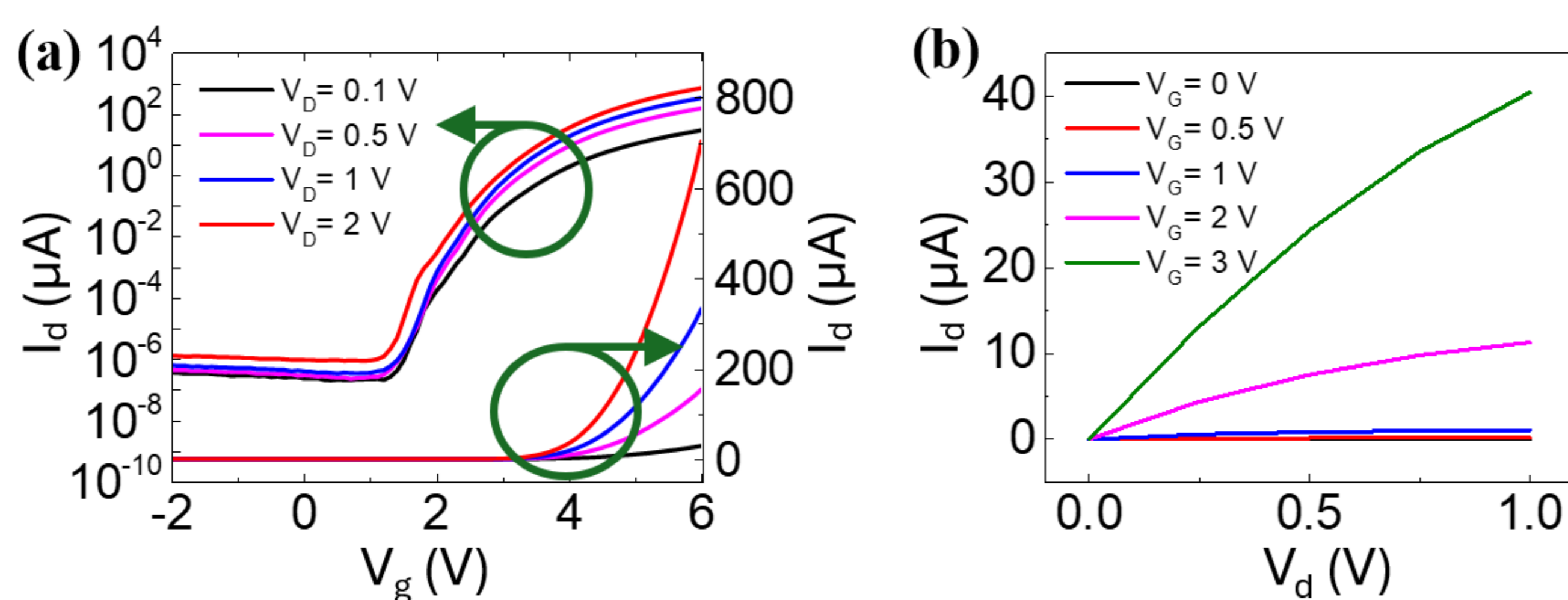


Fig. 3 (a) MoS<sub>2</sub> FDFET  $I_d$ - $V_g$  curve. (b) MoS<sub>2</sub> FDFET  $I_d$ - $V_d$  curve.

Table. 1 Benchmark table for MoS<sub>2</sub> FETs

Ref.	Mobility (cm <sup>2</sup> /V · s)	On/Off ratio	SS. (mV/decade)
[1]	N/A	1.02×10 <sup>5</sup>	117
[2]	217	10 <sup>8</sup>	74
[3]	1.5	2.3×10 <sup>6</sup>	N/A
[4]	700	10 <sup>7</sup>	95
[5]	34	2.5×10 <sup>6</sup>	N/A
[6]	150	10 <sup>8</sup>	60
This work	17.58	> 10 <sup>9</sup>	154

#### 2. Common-Gate CFET structure

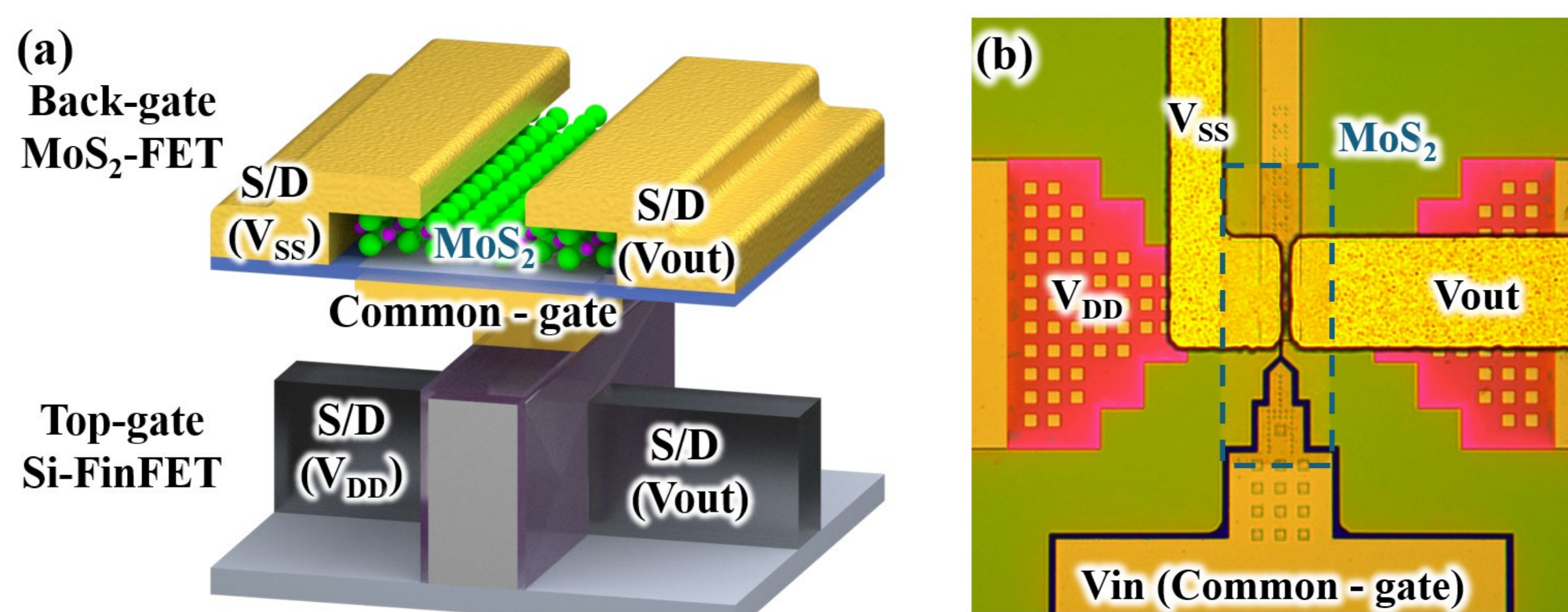


Fig. 4 (a) Common-gate architecture. (b) OM image.

### Experiment Results

#### 3. INV, NAND and NOR gates

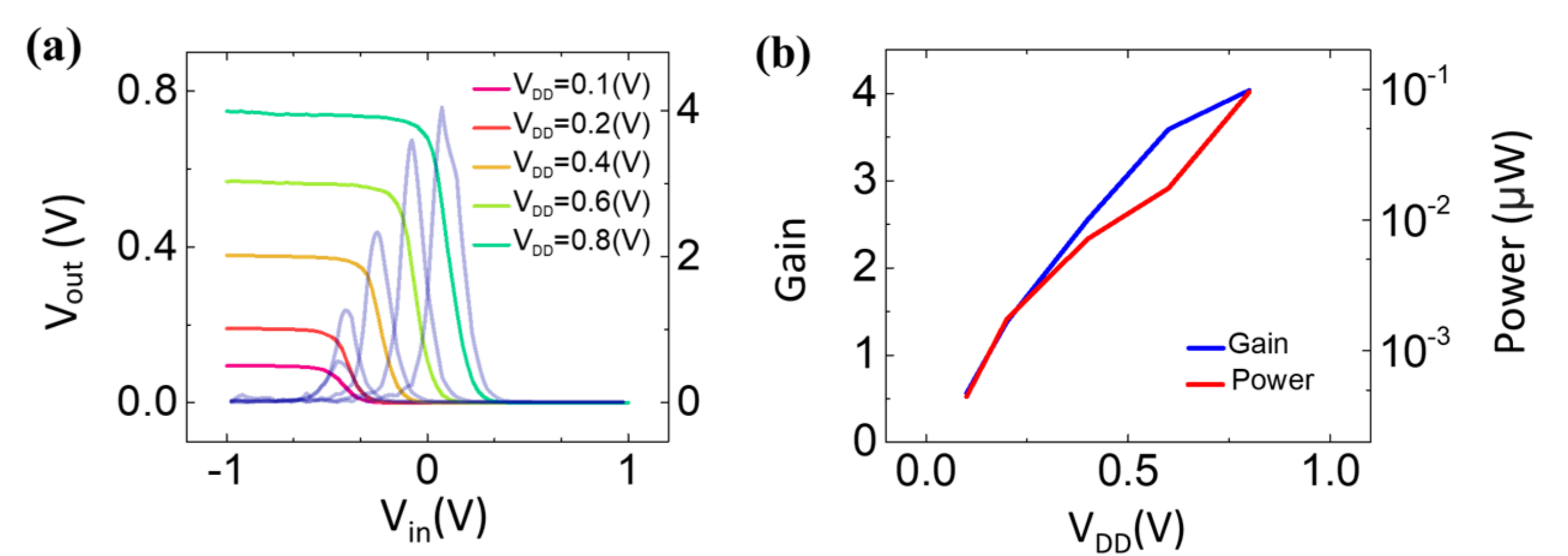


Fig. 5 (a) VTC of inverter. (b) Gain and power.

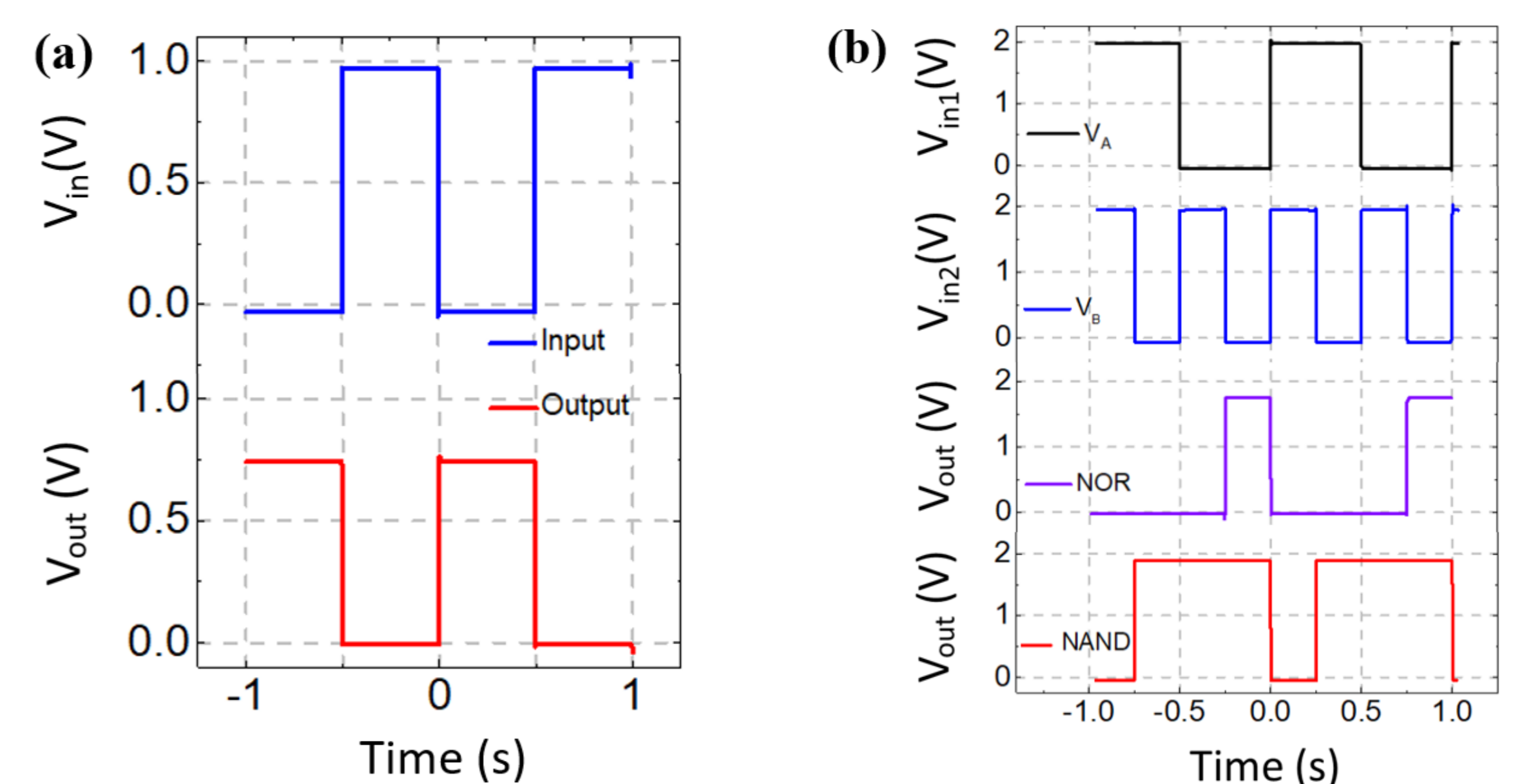


Fig. 6 (a) waveform of inverter. (b) waveform of NAND, NOR.

### Conclusion

- **High-performance MoS<sub>2</sub> Device:** MoS<sub>2</sub>-nFDFETs exhibit a high on/off ratio (>10<sup>9</sup>).
- **Heterogeneous Monolithic 3D Integration:** Demonstrate a BEOL compatible process and a M3D hetero-integration of MoS<sub>2</sub> and Si devices.
- **Functional CFET Logic Block:** Utilize CFET architecture to implement fundamental logic gates, e.g., INV, NAND and NOR.
- These highlight the advantages of 2D materials with M3D hetero-integration for the next-generation integrated circuit.